	CONNECTING CS INDUSTRIES	PC, Bannockb	ourn, Illinois. A	All rights reserved u ntions.	nder both	This docume level parts, t	ent is a declarat he declaration	ion of the second se	he substance asses all low	s within the er level ma	manufactur erials for wl	er listed it hich the m	em. Note: if anufacturer	the item is an as has engineering	ssembly with low responsibility.	
752-21.1					Form Type Distribute						eous Materia	erials and Mfg Information				
upplie	r Information															
ompany	name*	Company unique ID			-	Unique ID Authority					Response Date*					
nsemi												2024-05-18				
ontact N	Jame	Title - Contact				Phone - Contact*				Email - Contact*						
Product-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
uthorize	ed Representative*	Title - Representative				Phone - Representative*				Email - Representative*						
roduct-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	ective Date Version Manufacturing Sit		ring Site	v	Veight*	UOM	Unit Type		
		FDPF10N60NZ UF2 600V 7		UF2 600V 750mC	0mOhm TO220F		2024-05-18			СРА		2	107.333	mg	Each	
Ianufa	cturing Proccess Informa	tion														
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 M		L Rating	Peak Process Body Temperatu		ure Max Time at Peak Temper		Temperatu	ire Numbe	er of Reflow Cy	cles			
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30		second	ls 3						
omments	8															
or more	information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).							
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature	astislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	13.5	mg	Supplier	Silicon (Si)	7440-21-3		13.5	mg
Die Attach	4.013	mg	Supplier	Silver (Ag)	7440-22-4		0.0602	mg
			А	Lead (Pb)	7439-92-1	7a	3.7522	mg
			Supplier	Tin (Sn)	7440-31-5		0.2007	mg
lead Frame	1289.5	mg	Supplier	Silver (Ag)	7440-22-4		2.579	mg
			Supplier	Iron (Fe)	7439-89-6		1.2895	mg
			Supplier	Copper (Cu)	7440-50-8		1285.2446	mg
			Supplier	Phosphorus (P)	7723-14-0		0.3868	mg
Mold Compound	785.0	mg	Supplier	Polymer(phenyl glycidil ether)-co- dicyclopentadiene	119345-05-0		23.55	mg
			Supplier	Proprietary	Proprietary Data		11.775	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		39.25	mg
			Supplier	Carbon Black (C)	1333-86-4		3.925	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		117.75	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		39.25	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		549.5	mg
Plating	13.2	mg	Supplier	Tin (Sn)	7440-31-5		13.2	mg
Wire Bond - Al	2.12	mg	Supplier	Aluminum (Al)	7429-90-5		2.12	mg